



Advances in Inspection and Sensing Technologies

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Message from the Guest Editors

High-performance inspection and sensing technologies have become key enablers for advanced manufacturing, especially in the industries of semiconductor, consumer electronics, precision engineering, and fast-moving consumer goods (FMCG). As the frontier of data collection, these technologies are also the critical elements for Industry 4.0.

Inspection and sensing technologies have seen rapid development in the recent decade, driven by emerging concepts in the areas of electronics, optics, quantum physics, digitalization, and artificial intelligence.

As inspection and sensing applications involve multi-discipline topics, this Special Issue will welcome researchers from different areas to contribute high-quality submissions. The topics of interest will include, but not be limited to, the following:

- Intelligent inspection;
- Sensing technologies;
- Sensor fusion;
- Image/data fusion;
- Machine vision;
- Machine learning and deep learning;
- Condition monitoring and predictive maintenance;
- Non-destructive testing (NDT);
- Optics and photonics;
- In-line inspection and instrumentation;



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Message from the Editor-in-Chief

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